Y-170NFP

Dust Free & High Tg No-flow Prepreg

产品特点

- ●低树脂流动性，无卤 Tg180℃（DMA），
- ●加工无粉尘
- ●优良的耐热和耐化学性能
- ●低吸水性，耐 CAF 性能
- ●适用于无铅制程

应用领域

多层刚挠结合板、散热片粘合等

Key Features

- ●Low resin flow ,Halogen free and Tg180℃（DMA）
- ●Dust-free during processing
- ●Excellent thermal stability and Chemical Resistance
- ●Low water absorption and Anti-CAF capability
- ●Suitable for Lead-Free Process

Applications:

Multilayer rigid-flex boards,Heat sink bonding.etc

General Properties

Property	Item	IPC-TM-650	Test Condition	Units	Typical value
热性能 Thermal	玻璃化转变温度 Glass Transition Temperature	2.4.24.4	DMA	℃	180
	Z 轴方向膨胀系数 Z axis-CTE	2.4.24	TMA，Before TG	ppm/℃	32
			TMA，After TG	ppm/℃	270
			50～260℃	%	2.9
	288℃分层时间 T288	2.4.24.1	TMA	min	＞20
	260℃分层时间 T260	2.4.24.1	TMA	min	＞60
	288℃热冲击 Thermal stress	2.6.8	288℃，solder dip	S	＞300
	热失重(weight loss 5%) Decomposition temperature	2.4.24.6	TGA	℃	350
电性能 Electrical	体积电阻 Volume Resistivity	2.5.17.1	C-96/35/90	MΩ-cm	＞10^6
	表面电阻 Surface Resistivity	2.5.17.1	C-96/35/90	MΩ	＞10^6
	掉粉 Dust	HINNO test method	Internal standard	/	Dust free
	树脂流动性 Resin Flow	HINNO test method	Internal standard	mm	0.5

物理性能 Physical	弯曲强度 Flexural Strength LW	2.4.4	A	MPa	425
	弯曲强度 Flexural Strength CW	2.4.4	A	MPa	365
	剥离强度 Peel Strength（Hoz Copper Foil）	2.4.8	A	Kgf/cm	1.2
	剥离强度 Peel Strength（FCCL PI Side）	2.4.8	A	Kgf/cm	0.9
	尺寸稳定性 Dimensional Stability after thermal（MD/TD）	2.2.4	A	%	-0.06/-0.06
	吸水率 Moisture Absorption	2.6.2.1	D-24/23	%	0.15
	卤素含量 Halogen Content 氯 Chlorine 溴 Bromine 氯+溴 Chlorine+ Bromine	2.2.41	A	ppm	＜900 ＜900 ＜1500

Specimen thickness：0.4mm or 0.8mm.

Test Method is according to IPC TM-650 or National Standard Test Method.

The data above is only for reference, and the actual data will have deviation, according to varieties of test equipment and method.